SRF55Vxxx

Wafer specification

Document release reference: Z8F80901384-B

About this document

Scope and purpose

This document describes the SRF55Vxxx chip layout and provides product-specific data and information about the production sites.

The document is only valid in combination with the latest version of the general issue of the chip delivery specification for wafer (document number: Z8F50306400).

Intended audience

This document is intended for Infineon partners and customers who further process sawn wafers delivered by Infineon Technologies.

Important notes

Infineon ICs are extensively tested, but failure mechanisms according to chip-package interaction or solely package-related need to be evaluated and qualified by wafer/bare die customers. Refer to [1] and [2] accordingly.

The delivery form is intended for use in smart card packages only.

Table of contents

About this document 1
Important notes 1
Table of contents 2
1 Overview of wafer characteristics 3
A Chip layout, type 4
References 5
Revision history 6
Disclaimer 7

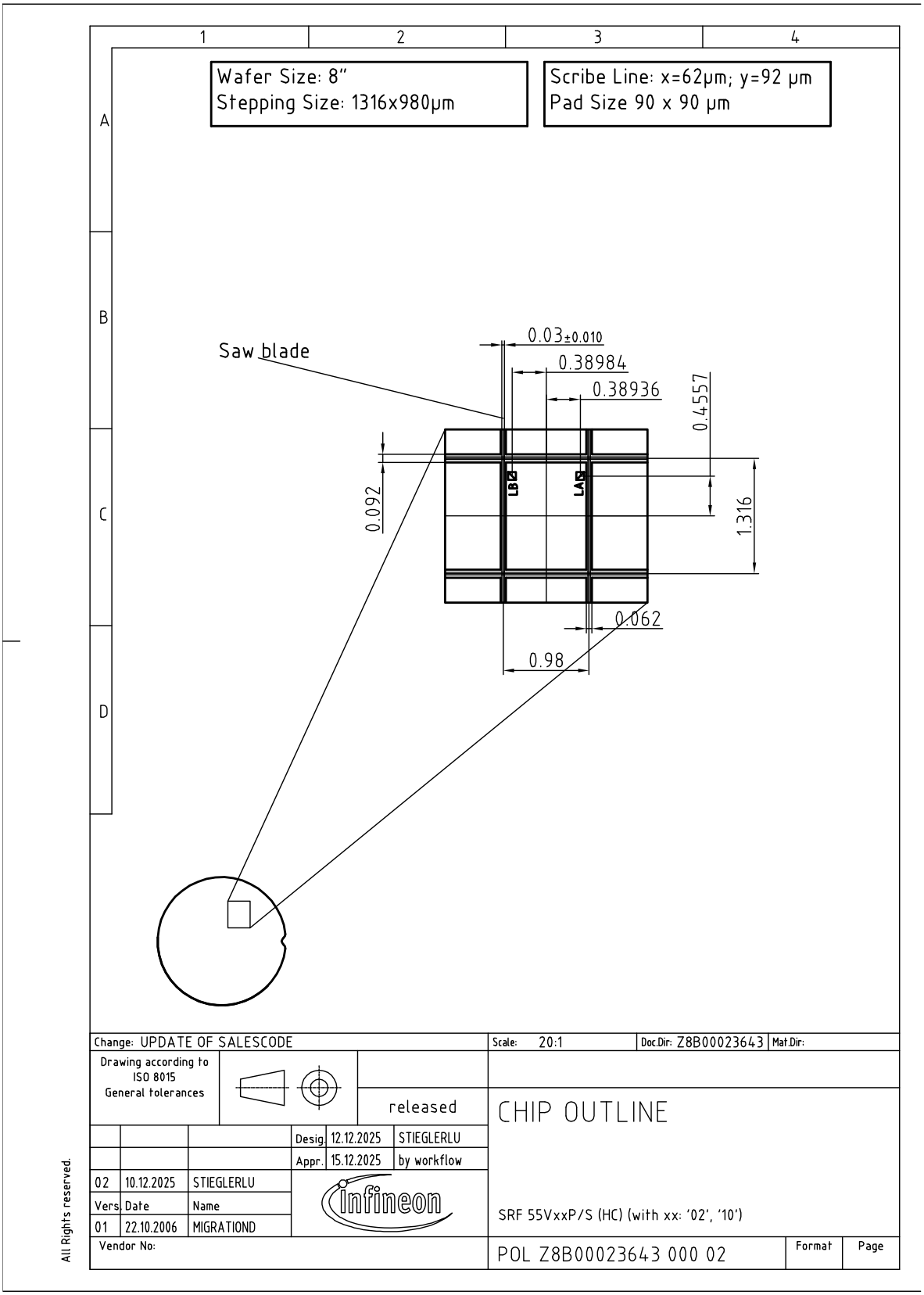
1 Overview of wafer characteristics

Table 1 Location: Dresden

Chip features	Description
Lot number coding	ZA...
Type	A
Stepping size	1.316 mm x 0.980 mm
Chip thickness[1)]	150 µm
Scribe line	x: 62 µm, y: 92 µm
Possible systems on wafer	21,860
Pad metallization material on front	AlCu
Pad metallization thickness on front	600 nm ± 60 nm
Passivation material and thickness	Plasmaoxide/Plasmanitride: 640 nm ± 60 nm Photoimide: 2.0 µm ± 0.5
Bonding area pad size	See chip layout
Bond pad material	AlCu
Recommended condition for die and wire bonding climate	23° C ± 1K, 30 – 60% rel. humidity

1) For tolerances, see the wafer delivery specification general issue[3]

A Chip layout, type



References

[1] JEDEC JEP156A: *Chip-Package Interaction Understanding, Identification, and Evaluation*; 2018-03

[2] JEDEC JEP122H: *Failure Mechanisms And Models For Semiconductor Devices Failure Mechanisms And Models For Semiconductor Devices*; 2016-09

[3] Infineon Technologies: *Wafer Specification - General Issue, Chip delivery specification for thinned 200 mm/300 mm wafer , unsawn/sawn (latest revision)*; document release reference: Z8F50306400

Revision history

Reference	Description
Revision 4.2, 2026-03-23	
	Editorial change only
Revision 4.1, 2026-02-24	
Overview of wafer characteristics	Added chip thickness
Revision 4.0, 2026-02-17 (Internal review)	
Whole document	New layout, changed document classification
Appendix A	Figure layout adaption
Revision 3.0, 2008-10-21	
	Revision
Revision 2.0, 2004-03-15	
	Revision
Revision 1.0, 2003-02-24	
	Initial version

Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

Edition 2026-03-23

Published by

Infineon Technologies AG

81726 Munich, Germany

© 2026 Infineon Technologies AG

All Rights Reserved.

Do you have a question about any aspect of this document?

Email:
CSSCustomerService@infineon.com

Document reference
IFX-kob1771333333727

Important notice

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

Warnings

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.